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**TITLE:** RESIN COMPOSITION AND CURED  
PRODUCT THEREOF  
**PUBN-DATE:** May 25, 1999

**INVENTOR-INFORMATION:**

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**ASSIGNEE-INFORMATION:**

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**ABSTRACT:**

PROBLEM TO BE SOLVED: To provide a resin compsn. and a cured product thereof which can be easily developed, possess excellent solvent resistance and plating solution resistance, possess heat resistance high enough to withstand soldering temps., and are particularly suitable for permanent resists of printed wiring boards.

SOLUTION: This resin compsn. and a cured product thereof comprise: an

epoxy (meth)acrylate resin obtd. by reacting an epoxy resin represented by the formula (where (n) is an average value and is a no. of 0 or more) with a monocarboxylic acid contg. an unsatd. group; and a diluent.

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